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PATENT NUMBER and ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10023723	12/21/2001	~~301~~ 257	778	~~2841~~ 2827	Talbott

**APPLICANTS: Chandran Biju; Gonzalez Carlos;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

PG-PUB	DO NOT PUBLISH ☐	RESCIND ☐

Foreign priority claimed ☐ yes ☐ no
35 USC 119 conditions met ☐ yes ☐ no
Verified and Acknowledged Examiners's intials

ATTORNEY DOCKET NO
219.40780X00

TITLE : Semiconductor package with low resistance package-to-die interconnect scheme for reduced die stresses

U.S.DEPT. OF COMM./PAT.& TM-PTO-436L(Rev. 12-94

NOTICE OF ALLOWANCE MAILED

Assistant Examiner

CLAIMS ALLOWED

Total Claims	Print Claim for O.G

ISSUE FEE

Amount Due	Date Paid

DRAWING

Sheets Drwg.	Figs.Drwg.	Print Fig

Primary Examiner

Application Examiner

☐ TERMINAL DISCLAMER

PREPARED FOR ISSUE

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